

## 650V Planar SiC Power MOSFET

### Features

- Wide Bandgap SiC MOSFET Technology
- Low On-Resistance with High Blocking Voltage
- Low Capacitances with High-Speed Switching
- Low Reverse Recovery (Qrr)
- Robust against Parasitic Turn on Even 0V Turn off Gate Voltage

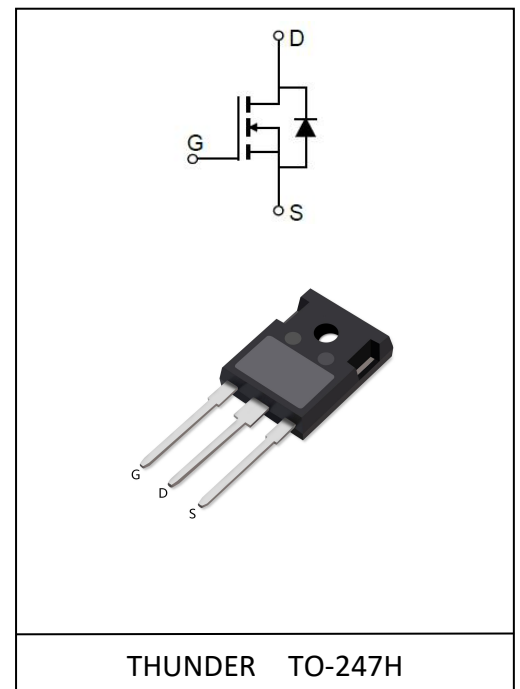
Parameter	Value	Unit	
$V_{DS}$	650	V	
$R_{DS(on)}_{typ.}$	$V_{GS}=15V$	90	mΩ
$I_D$	36	A	

### Benefits

- Reduced Switching Losses
- Increased System Switching Frequency
- Increased Power Density
- Reduction of Heat Sink Requirements
- Reduced EMI

### Application

- Switch Mode Power Supplies
- High Voltage DC/DC Converters
- Battery Chargers
- Motor Drives
- Pulsed Power Applications



### Maximum ratings at $T_j=25^\circ\text{C}$ , Unless otherwise specified

Parameter	Symbol	Test Condition	Value	Unit
Drain to Source Voltage	$V_{DS}$	$V_{GS}=0V, I_D=100\mu A$	650	V
Gate to Source Voltage	$V_{GS}$	Absolute maximum values	-10/+22	V
Recommended Operation Voltage of Gate to Source	$V_{GSOP}$	Recommended operational values	0/+18	V
Continuous Drain Current	$I_D$	$V_{GS}=15V, T_C=25^\circ\text{C}$	36	A
		$V_{GS}=15V, T_C=100^\circ\text{C}$	27	
Pulsed Drain Current	$I_{DM}$	$V_{GS}=15V, T_C=25^\circ\text{C}$	72	A

Power Dissipation	$P_{tot}$	$T_C=25^{\circ}\text{C}, T_J=175^{\circ}\text{C}$	136	W
Operating and Storage Temperature	$T_j, T_{stg}$		-55 to +175	$^{\circ}\text{C}$

## Thermal Characteristics

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
Thermal Resistance from Junction to Case	$R_{th(j-c)}$	-	1.1	-	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics

### Static Characteristics

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=500\mu\text{A}$	650			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=7.5\text{mA}$	2.7		4.5	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0\text{V}, V_{DS}=650\text{V}, T_J=25^{\circ}\text{C}$			10	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS}=18\text{V}, V_{DS}=0\text{V}$			250	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=15\text{V}, I_D=17\text{A}$		90	120	m $\Omega$
		$V_{GS}=15\text{V}, I_D=17\text{A}, T_J=175^{\circ}\text{C}$		77		
		$V_{GS}=18\text{V}, I_D=17\text{A}$		63		
		$V_{GS}=18\text{V}, I_D=17\text{A}, T_J=175^{\circ}\text{C}$		65		

### Dynamic Characteristics

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=500\text{V},$ $f=100\text{KHz}, T_J=25^{\circ}\text{C}$		1040		pF
Output Capacitance	$C_{oss}$			96		
Reverse Transfer Capacitance	$C_{rss}$			9		

Total Gate Charge	$Q_g$	$V_{GS}=0/15V, V_{DS}=500V,$ $I_D=17A, T_j=25^\circ C$		41	nC
Gate-Source Charge	$Q_{gs}$			10	
Gate-Drain Charge	$Q_{gd}$			16	
Gate Resistance	$R_g$	$V_{AC}=25mV, f=100KHz$		3.0	$\Omega$

### Switching Characteristics

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=0/15V, V_{DD}=500V,$ $I_D=17A, R_g=2\Omega$		19		nS
Rise Time	$t_r$			115		
Turn-Off Delay Time	$t_{d(off)}$			31		
Fall Time	$t_f$			34		

### Reverse Diode Characteristics

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=8.5A, T_j=25^\circ C$		3.5		V
Continuous Diode Forward Current	$I_S$	$V_{GS}=0V, T_j=25^\circ C$		36		A
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_{SD}=17A,$ $V_R=500V, di/dt=550A/us,$ $T_j=25^\circ C$		17.8		nS
Reverse Recovery Charge	$Q_{rr}$			63		nC
Peak Reverse Recovery Current	$I_{rrm}$			4.9		A

Typical Performance

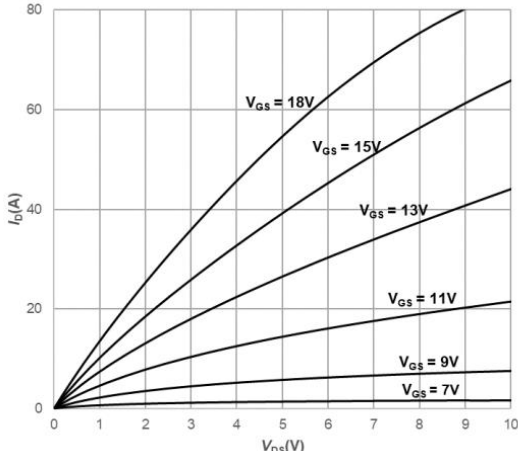


Fig1. Output Characteristics  $T_j=25^\circ\text{C}$

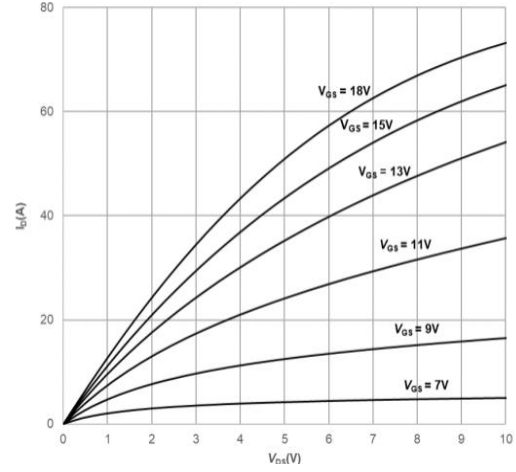


Fig2. Output Characteristics  $T_j=175^\circ\text{C}$

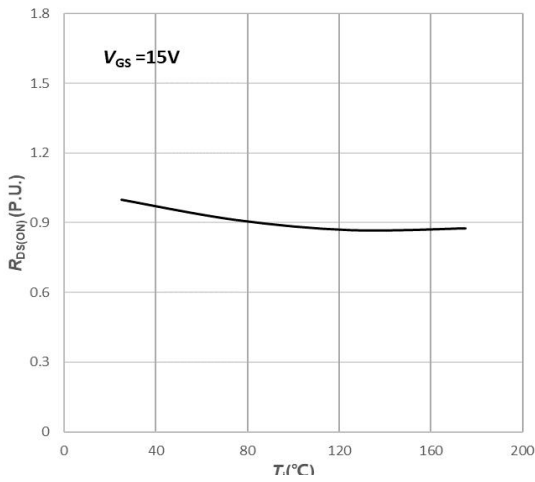


Fig4. Normalized On-Resistance vs. Temperature

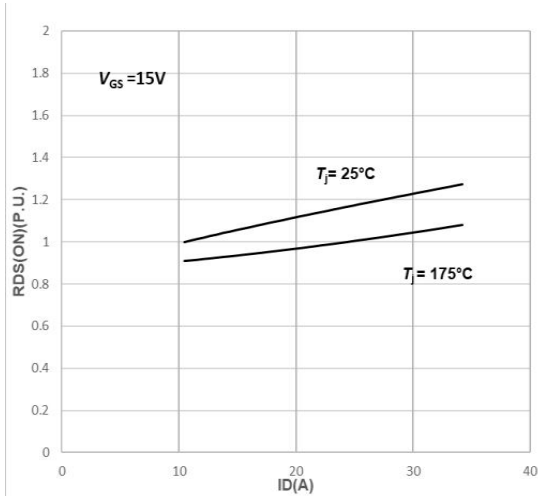
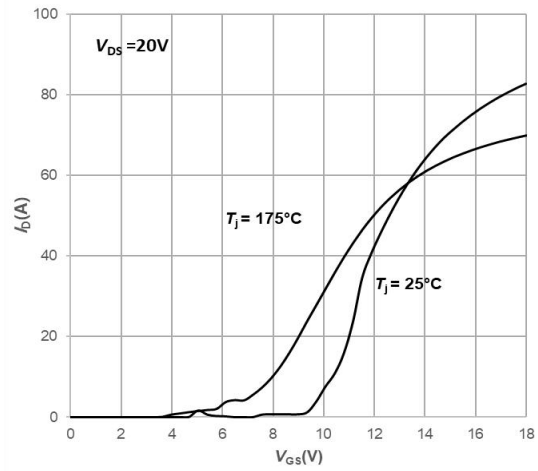


Fig5. Normalized On-Resistance vs. Drain Current For Various Temperatures

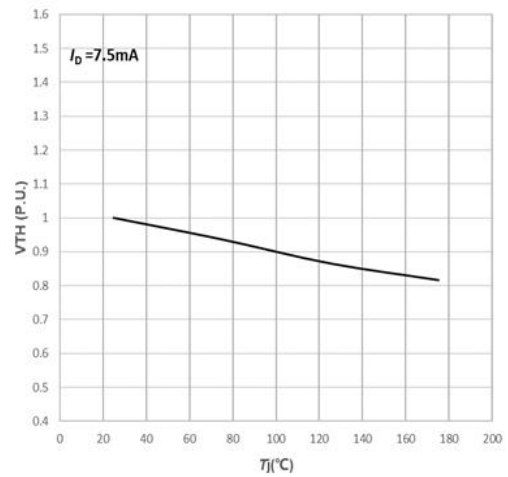


Fig6. Normalized Threshold Voltage vs. Temperature

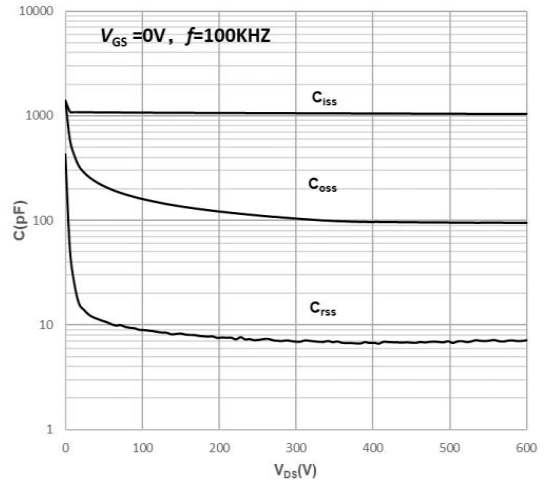
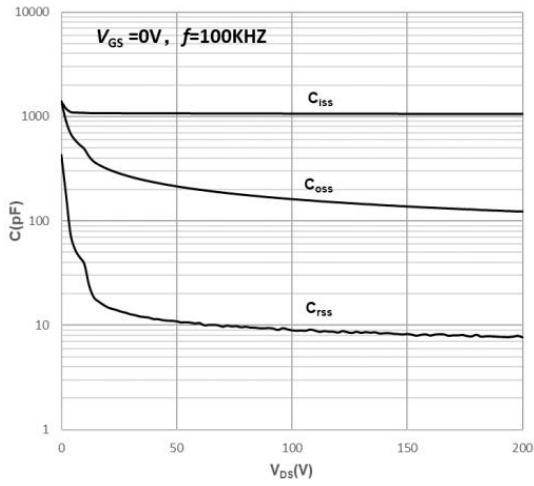


Fig7. Capacitances vs. Drain-Source Voltage (0-200V)

Fig8. Capacitances vs. Drain-Source Voltage (0-600V)

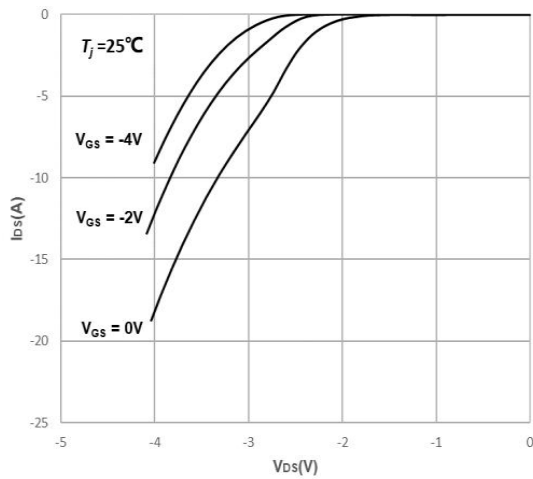
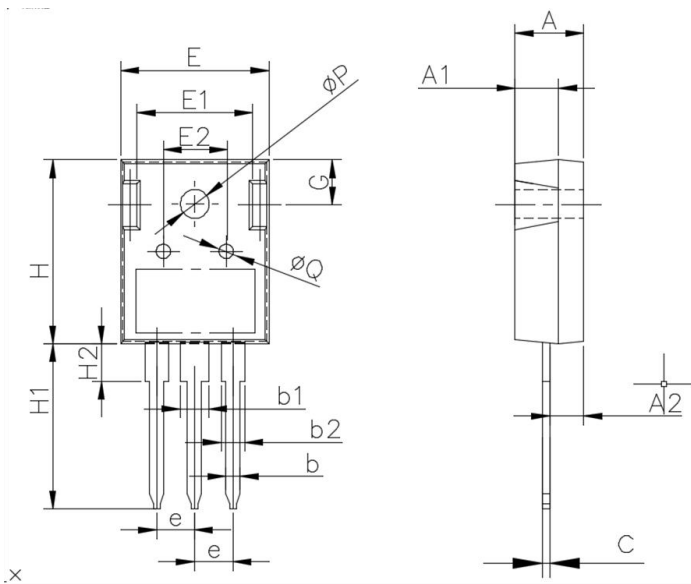


Fig9. Body Diode Characteristics

**Package Information**
**TO-247H PACKAGE**
**基本尺寸**


Symbol	单位 mm		
	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.80	3.00	3.20
A2	2.20	2.40	2.60
b	1.05	1.20	1.35
b1	2.80	3.00	3.20
b2	1.80	2.00	2.20
c	0.50	0.60	0.70
e	5.35	5.45	5.75
E	15.6	15.80	16.0
E1	12.3	12.50	12.7
E2	6.00	6.20	6.40
H	20.8	21.0	21.2
H1	19.5	20.0	20.5
H2	3.70	4.00	4.30
G	5.70	5.90	6.10
$\Phi P$	3.30	3.50	3.70
$\Phi Q$	2.30	2.50	2.70

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